

Ministry of Electronics & IT



SEMICON India 2026 Concludes Successfully, Showcasing India's Growing Role in the Global Semiconductor Ecosystem

Three-day event records more than 51,000 registrations and cumulative around 40,000 footfall; over 600 exhibitors, including participation from around 300 international companies

Representatives from 52 countries, 6 Country Pavilions and 12 State Pavilions bring together the global and domestic semiconductor ecosystem

56 MoUs / announcements and strategic initiatives across three days strengthen collaborations in design, manufacturing, packaging, materials, equipment, R&D, startups and talent

Posted On: 19 SEP 2026 10:20PM by PIB Delhi

SEMICON India 2026, the fifth edition of India's flagship semiconductor conference, concluded successfully today at Yashobhoomi, New Delhi, marking another step in the development of India's semiconductor ecosystem. Held from 17–19 September 2026 under the theme "Silicon to Systems: Building the Ecosystem," the event featured over 600 exhibitors, including around 300 international participants, representatives from 52 countries, and over 150 speakers. Six Country Pavilions representing Japan, South Korea, Malaysia, the Netherlands, Singapore and Sweden, along with 12 State Pavilions, a Startup Pavilion, Workforce Development Zone, Innovation Showcase & Student Hackathon, showcased different dimensions of the semiconductor value chain. The event recorded 51,656 total registrations and cumulative footfall of about 40,000.

Hon'ble Prime Minister Shri Narendra Modi inaugurated SEMICON India 2026 and highlighted India's progression from policy discussions and project planning to commercial semiconductor production. He interacted with young chip designers and students and virtually inaugurated commercial production lines at CDIL Semiconductor, Mohali, and Suchi Semicon, Surat, taking the number of operational commercial semiconductor units among the 12 projects approved under Semicon 1.0, to five. The Prime

Minister also outlined the transition to Semicon 2.0, aimed at developing capabilities across the semiconductor value chain. Semicon 2.0 has an outlay of ₹1,27,500 crore and is structured around six pillars - design, machines and materials, new fabs, advanced packaging, research and talent development.

The three days witnessed 56 MoUs, announcements and strategic initiatives, spanning semiconductor design, fabrication, advanced packaging, equipment and materials, power electronics, Artificial Intelligence (AI), High-Performance Computing (HPC), Research and Development (R&D), logistics, technology commercialisation, skilling and workforce development. Major announcements during the event included collaborations and investment plans involving semiconductor manufacturers, equipment and materials companies, design firms, academic institutions and skilling organisations.

Day 2 focused on translating the semiconductor mission into wider ecosystem development. Shri Ashwini Vaishnaw, Union Minister for Electronics and Information Technology, Railways, and Information & Broadcasting, outlined the implementation approach for Semicon 2.0, with emphasis on design, machines and materials, fabs, advanced packaging, applied R&D and talent. Deliberations during the day covered resilient supply chains, AI-enabled chip design and manufacturing, advanced packaging, indigenous R&D, power electronics, display technologies, workforce development and women's participation in semiconductor manufacturing. The discussions reflected the need to build not only fabrication capacity but the wider ecosystem of equipment, materials, gases, chemicals, precision manufacturing, intellectual property and skilled manpower required for a globally integrated semiconductor industry.

The concluding day focused on technological capability, industry collaboration, ease of doing business, sustainability, displays, workforce development and deep-tech startups. Discussions highlighted the need to strengthen scientific knowledge, materials, manufacturing know-how, research and talent alongside physical capacity. The Leadership Forum, moderated by Shri Amitesh Kumar Sinha, CEO, India Semiconductor Mission and Additional Secretary, MeitY, emphasised a coordinated "Silicon to Systems" approach linking semiconductor design and manufacturing with materials, equipment, packaging and electronics systems. Shri Sushil Pal, Joint Secretary, MeitY, moderated discussions on investment facilitation and ease of doing business, while other sessions covered sustainable manufacturing, advanced displays, deeper localisation and industry-ready skills across the semiconductor value chain.

The concluding day also placed strong emphasis on indigenous innovation and deep-tech entrepreneurship. Discussions examined ways to connect semiconductor research and intellectual property with procurement, patient capital, manufacturing and markets. The Digital India RISC-V Grand Challenge under the Chips to Startup Programme attracted 1,236 teams comprising 5,045 participants, with awards presented to top-performing teams for solutions developed using indigenous VEGA and SHAKTI processor-based System-on-Chips. The concluding programme also recognised Startup Pitch and Hackathon winners, reinforcing engagement among startups, students, investors and industry to support technology commercialisation and innovation. Three hackathons organised by KLA, Synopsys and Lam Research in partnership with CeNSE-IISc witnessed over 3,800 team registrations from more than 900 colleges, providing students opportunities to address industry-relevant semiconductor challenges. Winners were recognised through cash prizes, internships, software tools and compute credits.



International engagement remained a key feature across all three days through six Country Roundtables. On Day 1, the India–USA Roundtable brought together 180 participants, while the India–Japan Roundtable witnessed participation of 200 participants, with discussions focused on commercial partnerships, technology collaboration, equipment and materials, resilient supply chains and R&D. On Day 2, the India–Singapore Roundtable brought together 142 participants, the India–Europe Roundtable 139 participants, and the India–South Korea Roundtable 115 participants, advancing cooperation in manufacturing, advanced packaging, equipment and materials, investment, R&D and talent. On Day 3, the India–Malaysia Roundtable brought together around 150 participants, focusing on leveraging Malaysia’s established back-end semiconductor capabilities and India’s strengths in design, engineering and manufacturing to deepen partnerships across OSAT, advanced packaging, materials, equipment, supply chains and talent.



Across its three days, SEMICON India 2026 brought together the complete “Silicon to Systems” journey - design and intellectual property, materials and equipment, fabrication, advanced packaging, electronics manufacturing, R&D, startups, sustainability and talent. The scale of the 2026 edition represented a substantial expansion over SEMICON India 2025. With more than 600 exhibitors, around 300 international companies, participation from 52 countries, and 56 MoUs, announcements and strategic initiatives, SEMICON India 2026 provided a platform for investment, technology partnerships, commercialisation of research, industry–academia collaboration, startup development, skilling and international cooperation across the semiconductor value chain.

Vinod Kumar / Vineeth Narayan / Kanishk Sharma / Vanshita Jaiswal

(Release ID: 2312606) Visitor Counter : 1493

Read this release in: Urdu , हिन्दी